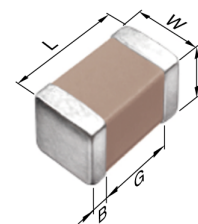


CGA4J1X7R0J685K125AC



TDK item description CGA4J1X7R0J685KT****

| | |
|---------------------|--|
| Applications | Automotive Grade |
| Feature | General General (Up to 50V) AEC-Q200 AEC-Q200 |
| Series | CGA4(2012) [EIA 0805] |
| Status | Production |



Dimensions in mm

| Size | |
|-------------------------------|--|
| Length(L) | 2.00mm ±0.20mm |
| Width(W) | 1.25mm ±0.20mm |
| Thickness(T) | 1.25mm ±0.20mm |
| Terminal Width(B) | 0.20mm Min. |
| Terminal Spacing(G) | 0.50mm Min. |
| Recommended Land Pattern (PA) | 1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering) |
| Recommended Land Pattern (PB) | 1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering) |
| Recommended Land Pattern (PC) | 0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering) |

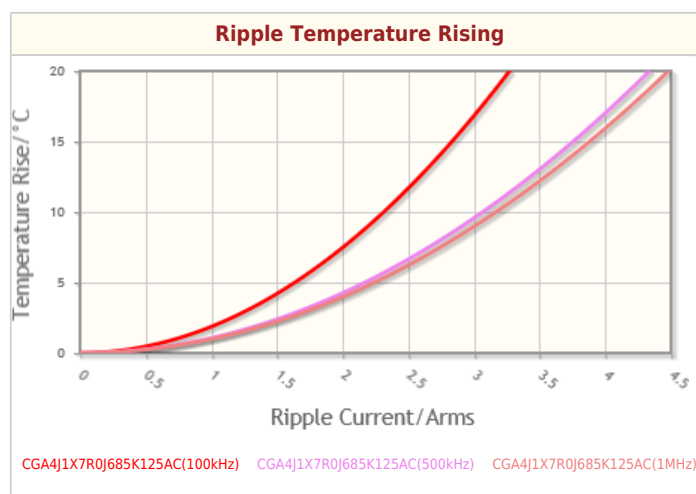
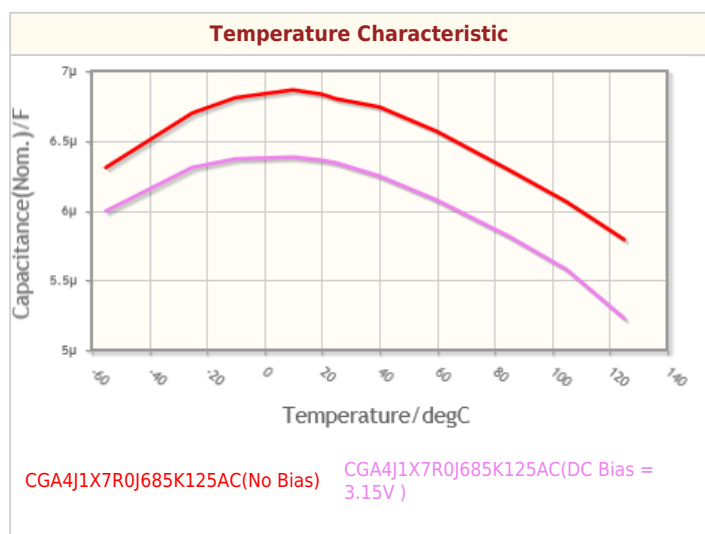
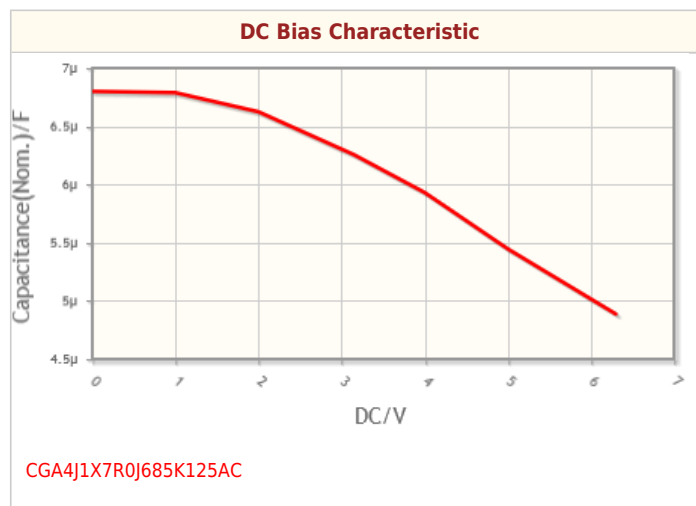
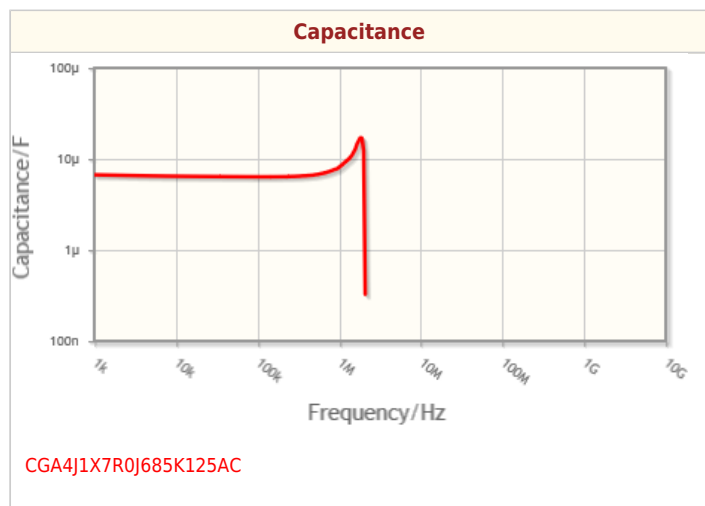
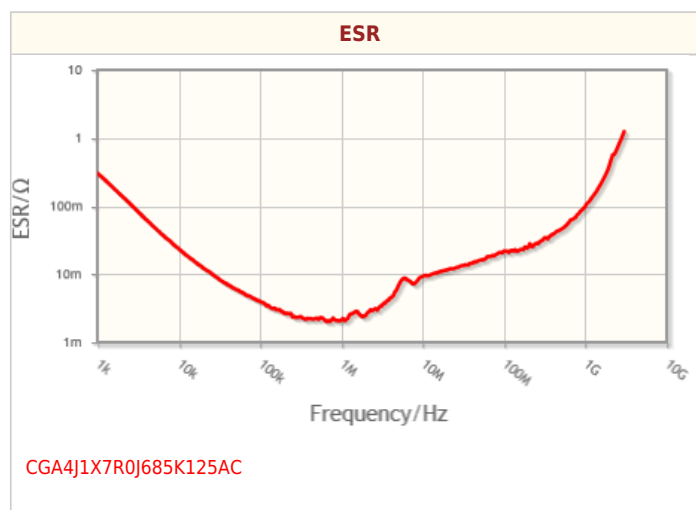
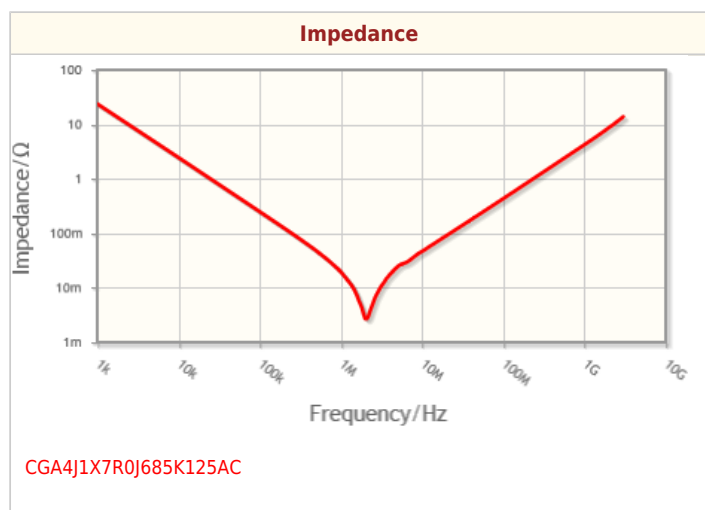
| Electrical Characteristics | |
|------------------------------|------------|
| Capacitance | 6.8μF ±10% |
| Rated Voltage | 6.3VDC |
| Temperature Characteristic | X7R(±15%) |
| Dissipation Factor (Max.) | 10% |
| Insulation Resistance (Min.) | 14MΩ |

| Other | |
|------------------|--------------------------------------|
| Soldering Method | Wave (Flow) Reflow |
| AEC-Q200 | Yes |
| Packing | Blister (Plastic)Taping [180mm Reel] |
| Package Quantity | 2000pcs |

CGA4J1X7R0J685K125AC

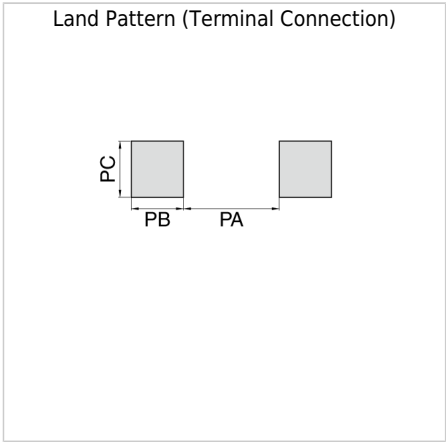


Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)





Associated Images



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.